

ACM
RESEARCH, INC.
Advanced Copper Metallization

April 1, 2008

To: Ms. Eleanor Cook
Board of Patent Appeals and Interferences
United States Patent and Trademark Office

From: David Hui Wang
ACM Research, Inc.

Subject: Patent Appeal No. 2007-2657 (Patent Application No. 09/837,911)

Dear Ms. Cook.

Per our telephone conversation yesterday, I would like to request to delay the hearing date from 4/8/2008 to after 4/15/2008 due to my business trip in Asia. I will return to bay are on 4/12, and will stay in bay area until 4/30.

Appreciate your understanding!

Yours truly,,

David Hui Wang
CEO and President
ACM Research, Inc.